

ALD precursors	Note
TMA	For Al ₂ O ₃ films
TiCl ₄	For TiO ₂ films
Electron beam evaporator pellets	Note
Al	For Lesker EBE1 and EBE2 tools
Cr	
Cu	
Ni	
Ti	
Etchants	Note
Al etchant	https://www.alfa.com/en/catalog/044581/
Buffered oxide etchant 7:1 (BoE)	
Cr etchant	https://www.alfa.com/en/catalog/044582/
Cu etchant	https://www.alfa.com/en/catalog/044583/
Liquid chemicals	Note
Acetone	
Hydrochloric acid (HCl)	
Hydrofluoric acid 49% (HF)	
Hydrogen peroxide 30%	
Isopropyl alcohol (IPA)	
Methanol	
Sulfuric acid (H ₂ SO ₄)	
Photoresists	Note
Shipley 1818	For Suss and EVG 610 mask aligners
AZ5214	For Suss and EVG 610 mask aligners
950 PMMA A4	For electron beam lithography
494 PMMA A4	For electron beam lithography
PGMEA	
Nanoscribe resins	Note
IP-Visio Photoresist	
IP-Q Photoresist	
IP-Dip Photoresist	
IP-L Photoresist	
IP-S Photoresist	
Lithography developers and strippers	Note
TMAH 25% in water	
AZ 400T stripper	
AZ developer 1:1	
AZ 300 MIF developer	
AZ 726 MIF developer	
MIBK/IPA developer	
MIF-319 developer	
Sputter Targets	Note
Au	For Cressington sputter coater
Al	For Lesker PVD75 DC tool
Cr	
Cu	
Ni	
Ti	
SiO ₂	For Lesker PVD75 RF tool
Al	For Clustex
Al ₂ O ₃	
Cu	
Hf	
Ir	
NbO ₂	
Nb ₂ O ₅	
Pt	
Si	
SiO ₂	
Ta	
Ti	
TiN	
TiO ₂	
Ru	
V ₂ O ₅	
VO ₂	
W	